



# Chem-Wik® Desoldering Braid

## Chem-Wik® Desoldering Braid

As the standard desoldering braid for service and repair, Chem-Wik® Desoldering Braid ensures fast and safe desoldering. The ultra-pure, oxygen free copper braid quickly and completely removes solder from circuit boards and components. Its fast wicking action protects components from harmful heat damage. PermaPak™ Barrier Packaging ensures ultimate braid freshness and speed by sealing out harmful effects of the environment and protecting against oxidation.

### Chem-Wik® Desoldering Braid:

Meets or exceeds the greatest range of performance standards:

- MIL-F-14256F Type R
- NASA STD-8739.3 Soldered Electrical Connections
- ANSI/IPC J STD-004, Type ROLO

### Static Dissipative Packaging:

- DOD Standard 1686C and MIL-HDBK-263B
- Mil-Std-2000A
- Mil-B-81705C Static Decay Rate Provision

### Chem-Wik® Rosin

The fast, safe rosin flux desoldering braid for removing solder from leads and components

- Coated with ultra high purity rosin
- Quickly and thoroughly removes solder
- Noncorrosive Type R rosin flux

### Chem-Wik® Rosin SD

The fast, safe rosin flux desoldering braid packaged in static dissipative bobbins

- Reduces the risk of damage associated with static electricity
- Coated with noncorrosive ultra high purity Type R rosin flux
- Quickly and thoroughly removes solder



PermaPak™ Barrier Packaging contains 25 bobbins per package

## Chem-Wik® Product Selection Guide

PRODUCT	COLOR	SIZE	5' 1.5m	25' 7.5m	50' 15.0m	100' 30.5m	500' 152.5m	APPLICATION
Chem-Wik® Rosin	Gray	.030"/0.8mm		2-25L	2-50L	2-100L	2-500L	Micro-Circuits
	Yellow	.050"/1.3mm		5-25L	5-50L	5-100L	5-500L	Small Pads
	Green	.075"/1.9mm		7-25L	7-50L	7-100L	7-500L	Medium Pads
	Blue	.100"/2.5mm		10-25L	10-50L	10-100L	10-500L	Large Pads
Chem-Wik® Rosin SD	Gray	.030"/0.8mm	2-5L					Micro-Circuits
	Yellow	.050"/1.3mm	5-5L					Small Pads
	Green	.075"/1.9mm	7-5L					Medium Pads
	Blue	.100"/2.5mm	10-5L					Large Pads

Distributed by:



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## Desoldering Applications



### Wire Wrap Pins

Desolder pins for easy removal. Removes solder buildup. Eliminates potential intermittent problems.



### Lugs/Posts

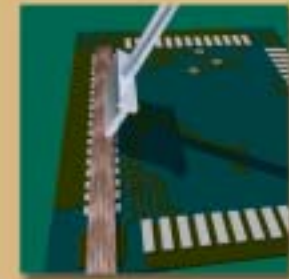
Wicks solder completely, eliminating solder splash or drip. Leaves terminal fluxed and ready for resoldering.



### Components

Easily removes solder from components with straight or clinched leads. Minimum heat required. No damage to board or components.

## Cleaning Applications



### SMT Pads

Quickly and safely desolders entire rows of SMT pads. Applications-specific sizes desolder individual fine-pitch SMT pads.



### BGA Pads

Safely removes solder from BGA pads and chips in three to four passes. Completely removes all residual solder and facilitates chip repositioning.



### Solder Bridges

Completely removes solder bridges. Eliminates potential shorts. No damage to boards or circuitry.



### Clean Script

Selectively retouches etched script. Improves aesthetic appearance. Eliminates secondary identification. Easy to use.



### Blobs

Eliminates and removes blobs as well as shorts and icicles. Leaves circuitry smooth. Cleans potential problem areas.



### Finger Connectors

Cleans finger connectors and surface mount pads.

## Braid Sizes

BGA	Purple	
.030"/0.8mm	White	
.060"/1.5mm	Yellow	
.080"/2.0mm	Green	
.110"/2.8mm	Blue	
.145"/3.7mm	Brown	
.210"/5.3mm	Red	



The Leader in  
Desoldering Technology

